

<b>PCN Number:</b>	<b>20260630000.1</b>	<b>PCN Issued</b>	July 01, 2026
Qualification of TI Clark as an additional Assembly site for select devices		<b>Sample request deadline:</b>	August 30, 2026
		<b>Estimated 1<sup>st</sup> ship date:</b>	September 29, 2026
<b>August 30, 2026* will not be supported.</b>			

<b>Change type(s)</b>
Assembly Site

**PCN Details**

<b>Description of Change:</b>						
Texas Instruments is pleased to announce the qualification of TI Clark as an additional Assembly site for select devices. No material differences between sites.						
<table border="1"> <thead> <tr> <th></th> <th><b>Current Site</b></th> <th><b>Additional Site</b></th> </tr> </thead> <tbody> <tr> <td>Assembly site</td> <td>CDAT</td> <td>CLARK</td> </tr> </tbody> </table>		<b>Current Site</b>	<b>Additional Site</b>	Assembly site	CDAT	CLARK
	<b>Current Site</b>	<b>Additional Site</b>				
Assembly site	CDAT	CLARK				
Qual details are provided in the Qual Data Section.						
<b>Reason for Change:</b>	Continuity of Supply					

<b>Anticipated impact on Form, Fit, Function, Quality or Reliability:</b>	Review the Standard Data Packet for more details on the changes												
<b>Impact on Environmental Ratings</b>	<p>Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.</p> <table border="1"> <thead> <tr> <th><b>RoHS</b></th> <th><b>REACH</b></th> <th><b>Green Status</b></th> <th><b>IEC 62474</b></th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>	<b>RoHS</b>	<b>REACH</b>	<b>Green Status</b>	<b>IEC 62474</b>	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change				
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<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change										
<b>Changes to product identification resulting from this PCN:</b>	<p><b>Assembly Site Information</b></p> <table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>Assembly Country Code (23L)</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>CDAT</td> <td>CDA</td> <td>CHN</td> <td>Chengdu</td> </tr> <tr> <td>TI Clark</td> <td>QAB</td> <td>PHL</td> <td>Pampanga</td> </tr> </tbody> </table>	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	CDAT	CDA	CHN	Chengdu	TI Clark	QAB	PHL	Pampanga
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City										
CDAT	CDA	CHN	Chengdu										
TI Clark	QAB	PHL	Pampanga										

Sample product shipping label (not actual product label):



**Products Affected:**

LMR38015FDRRR	LMR38025FDRRR
LMR38015SDRRR	LMR38025SDRRR

**Qualification Report**  
**Automotive Qualification Summary**  
**(As per AEC-Q100 Rev. J and JEDEC Guidelines)**  
 Approve Date 09-June-2026

**Product Attributes**

Attributes	Qual Device: <u>LMR38025SQDRRRQ1</u>	QBS Package Reference: <u>LM5165QDRCRQ1</u>	QBS Package Reference: <u>LM5157QRTERQ1</u>	QBS Package Reference: <u>TPS6521930WRHBRO1</u>	QBS Package Reference: <u>DRV8316CRORGFRQ1</u>
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Power Management	Power Management	Power Management
Wafer Fab Supplier	RFAB	RFAB	RFAB	RFAB	RFAB
Assembly Site	CLARK-AT	CLARK-AT	CLARK-AT	CLARK-AT	CLARK-AT
Package Group	QFN	QFN	QFN	QFN	QFN
Package Designator	DRR	DRC	RTE	RHB	RGF
Pin Count	12	10	16	32	40

QBS: Qual By Similarity, also known as Generic Data  
 Qual Device LMR38025SQDRRRQ1 is qualified at MSL2 260C

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>LMR38025SQDRRRQ1</u>	QBS Package Reference: <u>LM5165QDRCRQ1</u>	QBS Package Reference: <u>LM5157QRTERQ1</u>	QBS Package Reference: <u>TPS6521930WRHBRO1</u>	QBS Package Reference: <u>DRV8316CRORGFRQ1</u>
<b>Test Group A - Accelerated Environment Stress Tests</b>												
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	QBS	3/0/0	3/0/0	3/574/4 <sup>1,2,3</sup>	3/0/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	QBS	3/231/0	3/231/0	1/77/0	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	110C/85%RH	264 Hours	QBS	3/231/0	-	-	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	QBS	-	3/231/0	1/77/0	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	QBS	3/231/0	3/231/0	3/231/1	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	QBS	-	1/5/0	1/5/0	1/5/0

PTC	A5	JEDEC JESD22-A105	1	45	PTC	-40/125C	1000 Cycles	Not Applicable	1/45/0	-	-	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	QBS	-	-	1/45/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	QBS	3/135/0	-	-	-
<b>Test Group B - Accelerated Lifetime Simulation Tests</b>												
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	-	-	-
All other group B tests are carried over from original Q100 product qualification.												
<b>Test Group C - Package Assembly Integrity Tests</b>												
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0	1/30/0	1/300
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0	1/30/0	1/300
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	Generic data applied	1/15/0	1/15/0	-	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	3/30/0	3/30/0	1/10/0	1/100
<b>Test Group D - Die Fabrication Reliability Tests</b>												
EM	D1	JESD61	-	-	Electromigration	-	-	All other group D test are carried over by original Q100 product qualification. Not applicable to assembly site change.	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDD	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-		Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-		Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-		Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-		Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
<b>Test Group E - Electrical Verification Tests</b>												
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	All Device specific tests are carried over from original Q100 product qualification.				
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 volts					
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-					
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-		-	-	1/30/0	1/30/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

**Ambient Operating Temperature by Automotive Grade Level:**

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

**E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2505-012

[1]-EOS/EIPD due to handling, unrelated to stress  
8D available

[2]-EOS/EIPD due to handling, unrelated to stress  
8D available

[3]-EOS/EIPD due to handling, unrelated to stress  
8D available

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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